



# SOT1399-1

WLCSP24, wafer level chip-scale package; 24 bumps; 2.98 mm x 1.90 mm x 0.525 mm body (backside coating included)

13 July 2017

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP24
<b>Package type industry code</b>	WLSCP24
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	22-6-2017
<b>Manufacturer package code</b>	SOT1399

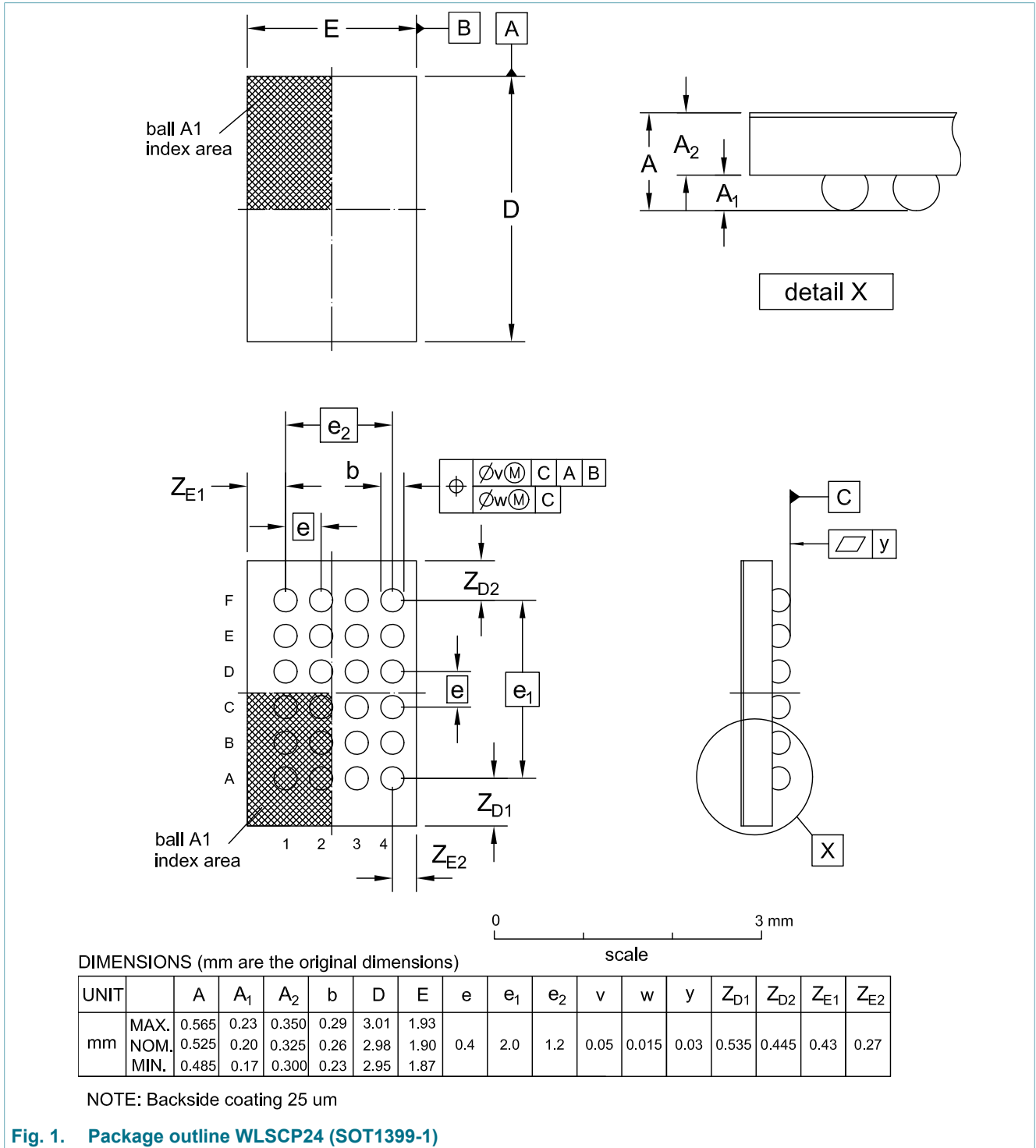
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	2.95	-	2.98	3.01	mm
E	package width	1.87	-	1.9	1.93	mm
A	seated height	0.485	-	0.525	0.565	mm
A <sub>2</sub>	package height	0.3	-	0.325	0.35	mm
e	nominal pitch	-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	24	-	



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## 2. Package outline



WLCSP24, wafer level chip-scale package; 24 bumps; 2.98 mm x 1.90 mm x 0.525 mm body (backside coating included)

### 3. Soldering

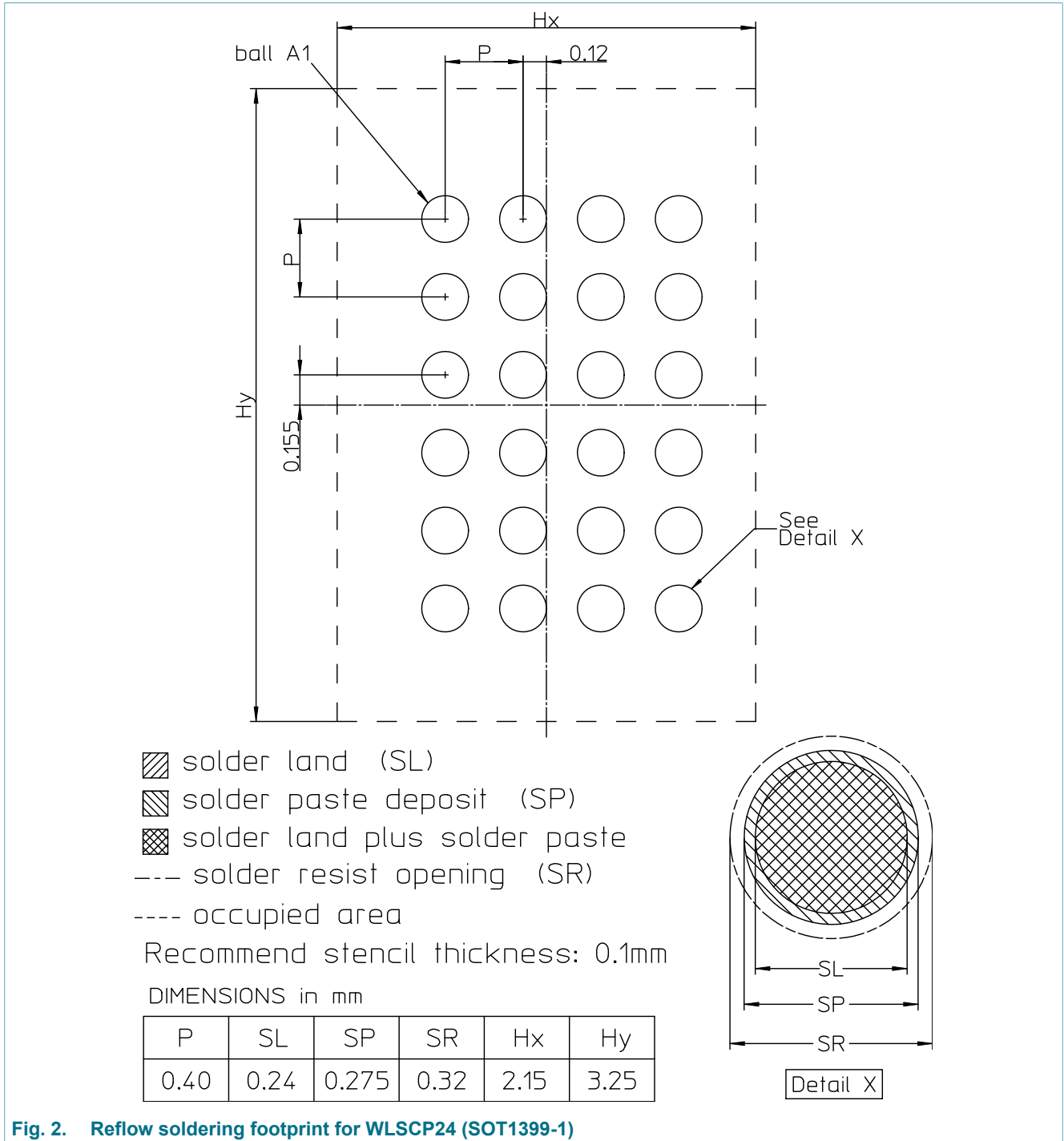


Fig. 2. Reflow soldering footprint for WLCSP24 (SOT1399-1)

WLCSP24, wafer level chip-scale package; 24 bumps; 2.98 mm x 1.90 mm x 0.525 mm body (backside coating included)

## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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For sales office addresses, please send an email to: [salesaddresses@nxp.com](mailto:salesaddresses@nxp.com)  
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